

2016 Applied Materials Technical Symposium:

Exploring Advanced Metrology and Inspection for Process Control

Dec. 15, 2016, Shangri-La Tokyo

Time		Title	Presenter
13:00	13:10	Opening & Welcome	Kenji Aoyama, Applied Materials
13:10	13:50	Inspection and Metrology for the Japanese Semiconductor Industry	Ram Peltinov, Applied Materials
13:50	14:30	Manufacturing Innovation of Semiconductor Memory by Utilization of Big Data	Hiroshi Akahori, Toshiba
14:30	14:50	Break	
14:50	15:20	All-Around CD-SEM Metrology for HAR, 3D, and Conventional Applications	Roi Meir, Applied Materials
15:20	15:50	Advanced Multi-Application Optical Wafer Inspection	Oren Faigenzvaig, Applied Materials
15:50	16:20	Industry-Leading Capabilities for SEM Defect Review	Roy Mizrahi, Applied Materials
16:20	16:50	Get More Out of Your Install Base – SEMVision™ G3E and Inline FIB	Daniel Harel, Applied Materials
16:50	17:00	Closing	William Kuo, Applied Materials
17:00	19:00	Poster Session & Reception	